

SHINDENGEN

General Purpose Rectifiers

SMT Bridges

S1ZB60

600V 0.8A

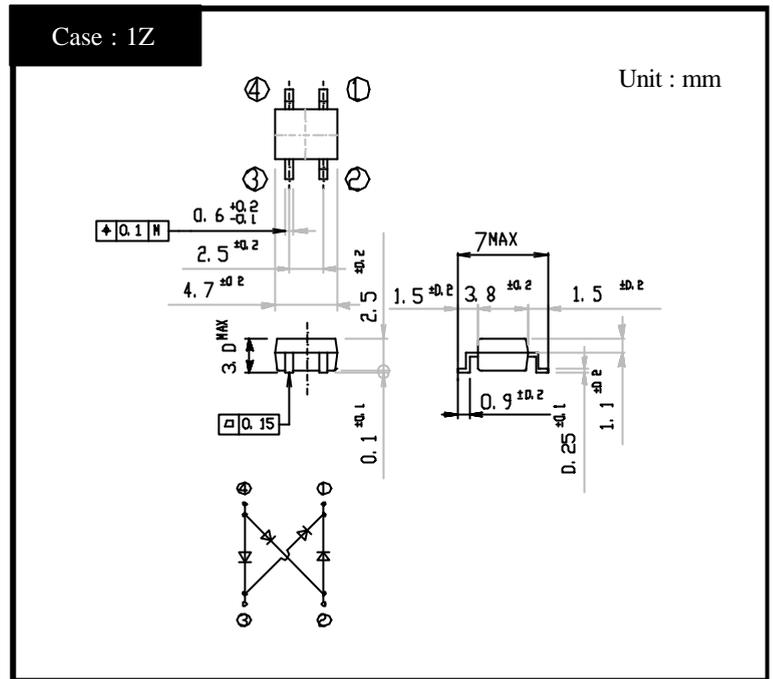
FEATURES

- Small SMT package
- High reliability with superior moisture resistance
- Applicable to Automatic Insertion

APPLICATION

- Switching power supply
- Home Appliances, Office Equipment
- Telecommunication, Factory Automation

OUTLINE DIMENSIONS



RATINGS

Absolute Maximum Ratings (If not specified Tl=25)

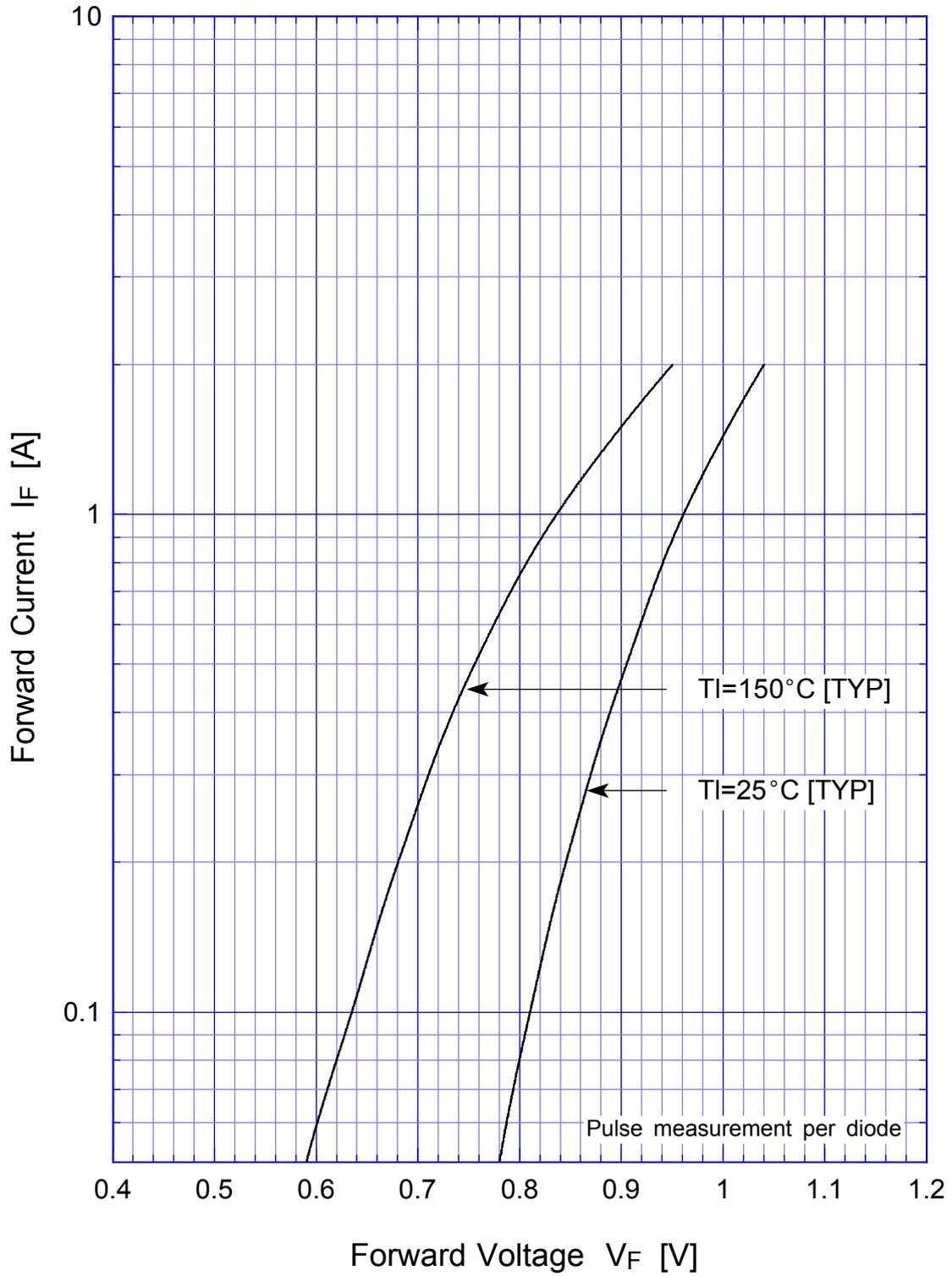
Item	Symbol	Conditions	Ratings	Unit
Storage Temperature	Tstg		-40 ~ 150	
Operating Junction Temperature	Tj		150	
Maximum Reverse Voltage	V _{RM}		600	V
Average Rectified Forward Current	I _O	50Hz sine wave, R-load On alumina substrate Ta=25	0.8	A
		50Hz sine wave, R-load On glass-epoxy substrate Ta=25	0.5	
Peak Surge Forward Current	I _{FSM}	50Hz sine wave, Non-repetitive 1 cycle peak value, Tj=25	30	A
Current Squared Time	I ² t	1ms t < 10ms Tj=25	4.5	A ² s

Electrical Characteristics (If not specified Tl=25)

Item	Symbol	Conditions	Ratings	Unit
Forward Voltage	V _F	I _F =0.4A, Pulse measurement, Rating of per diode	Max.1.05	V
Reverse Current	I _R	V _R =V _{RM} , Pulse measurement, Rating of per diode	Max.10	μA
Thermal Resistance	j-l	junction to lead	Max.20	/W
		junction to ambient On alumina substrate	Max.76	
		junction to ambient On glass-epoxy substrate	Max.134	

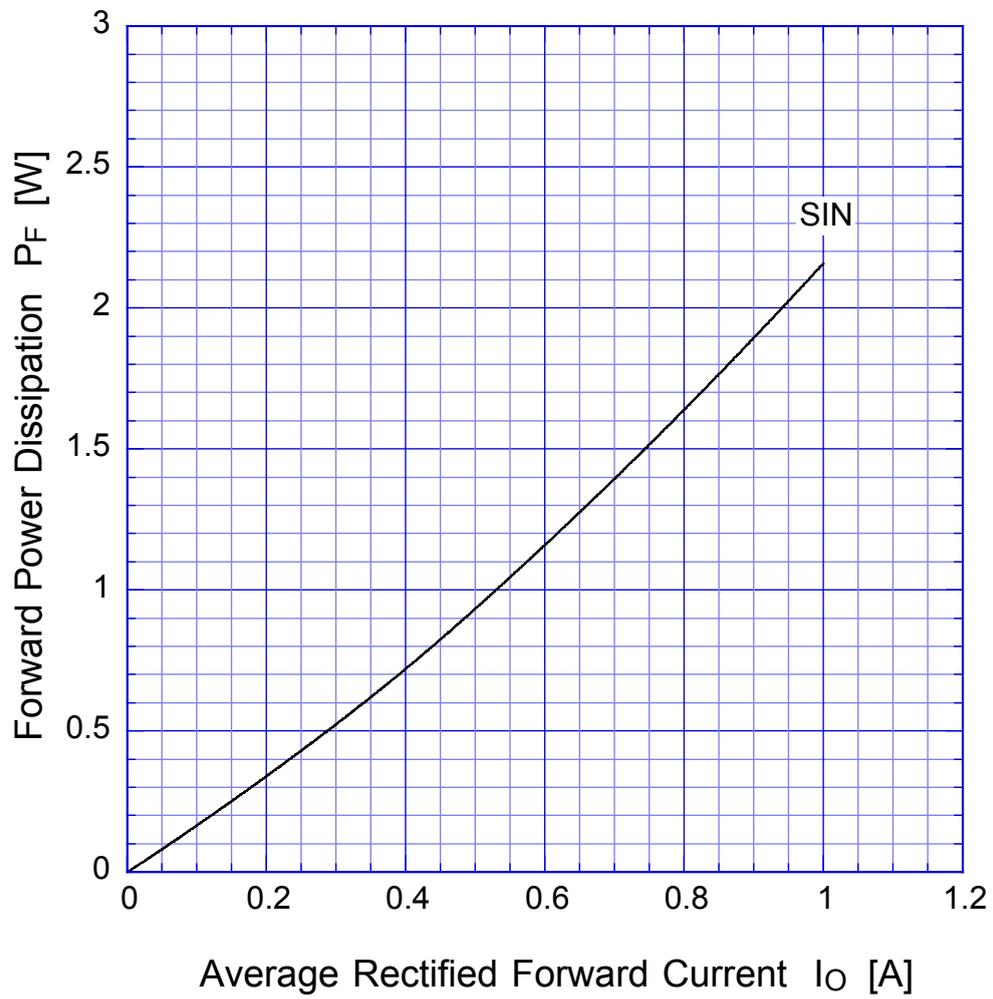
S1ZBx

Forward Voltage



S1ZBx

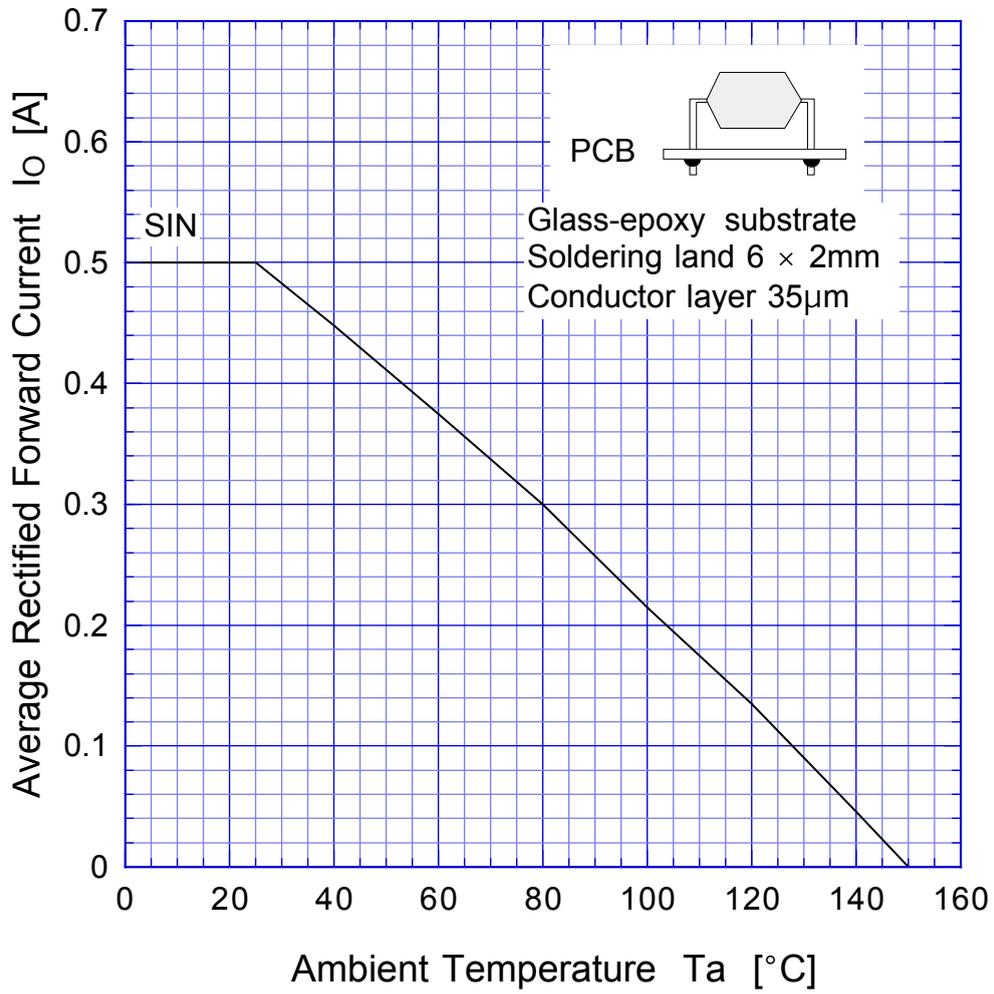
Forward Power Dissipation



$T_j = 150^\circ\text{C}$
Sine wave

S1ZBx

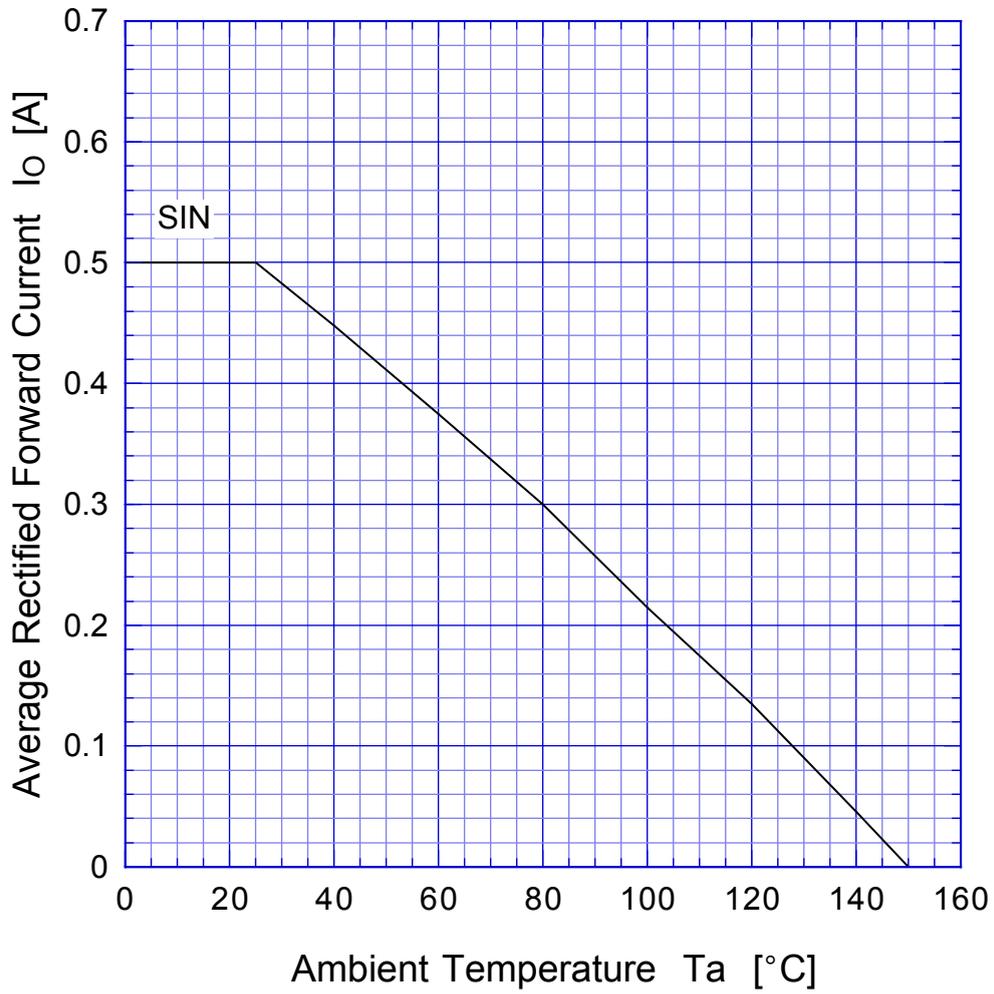
Derating Curve



Sine wave
R-load
Free in air

S1ZBx

Derating Curve



Sine wave
R-load
Free in air

	Glass-epoxy	Alumina
Soldering land	1 mm	1 mm
Conductor layer	35 μ m	20 μ m
Substrate thickness		0.64 mm

S1ZBx

Peak Surge Forward Capability

